

# WEST·BOND, INC.



**4530E – 4630E SERIES (High Frequency)**

**SEMI-AUTOMATIC WIRE BONDERS**

*Continuing a Tradition of Quality*

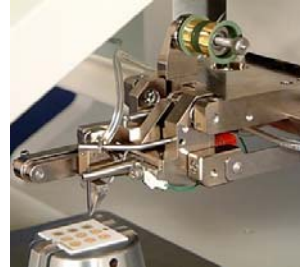
# 4530E - 4630E Series High Frequency Semi-Automatic Bonders

**4530E - 45° Wire Feed Wedge Bonder (High Frequency)**  
**4630E - 90° Wire and Ribbon Feed Wedge Bonder (High Frequency)**



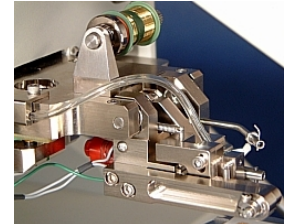
**AUTOMATIC PRECISION** at a fraction of the cost. Microprocessor controlled motor drives for both Y and Z-axes bond a succession of parallel, single or multiple arched wires maintaining identical loop and bond shapes. Unlimited deep-reach access to bond targets on IC packages of any X-Y dimension with WestBond's throatless chassis and micromanipulator designs. Ideal for bonding high power, high frequency devices where identical bond and loop shapes are critical.

**CONVERTIBILITY** for angled and vertical wire feed wedge bonding is easily accomplished with a simple change of clamping mechanisms, both of which are included with Model 454630E. Model 4546E expands convertibility with a 45° tool head and 90° tool head. All program variables and bond settings for each configuration are retained in memory between conversions.



**PROGRAMMING** for different types of wire connections are entered into separate buffers, each with individual ultrasonic power, time, force (high or low) and loop control data. Each type may have up to 100 bonds, and may be repeated for any number of wires for up to a maximum of 6,000 individual bonds. Program values, action prompts and fault diagnostics are exhibited on the easy to read 4 line, 40 character LCD sequentially with machine operation.

**ADDITIONAL FEATURES** include 63 kHz ultrasonics, orthogonal X-Y-Z axes with pure vertical Z, color video and microscope targeting, motion slaved Z encoder, pneumatic braking of X-Y-Z axes during bonding, and built-in tool heat. Available with the base and work platform for tabletop applications, or without base and work platform for mounting above any work handling system.



## STANDARD SPECIFICATIONS:

CONTROL LOGIC: Motorola 68000 microprocessor  
MEMORY: 256KB RAM  
DATA ENTRY: Keypad - 12 keys  
DISPLAY: 4 line, 40 character LCD  
DEVICE STORAGE: Battery Backup RAM  
MONITOR: LCD Flat Screen  
TOOL Z STROKE: 0.5 inch  
TOOL Y STROKE: 0.5 inch  
MOTORIZED Z RESOLUTION: 0.000208 inch per micro-step  
MOTORIZED Y RESOLUTION: 0.000208 inch per micro-step  
MANUAL Z ENCODER RESOLUTION: 0.001 inch  
FORCE RANGE: Adjustable, 10-250 grams,  
BOND FORCE: Two levels, adjustable  
TRANSDUCER: ½ wave, 63 kHz (nominal)

ULTRASONICS: Built-in, 8 bit, 5 watts  
ESD PROTECTION: Protection against Electrostatic Discharge  
TAIL AND PULL STROKES: Programmable  
ANGLED FEED TOOL LENGTH: 0.750 inch  
VERTICAL FEED TOOL LENGTH: 0.750 inch  
WIRE RANGE: 0.7 to 2 mils, ½ x10 mil gold ribbon (vertical feed)  
WIRE SPOOL MOUNT: 0.5 inch with ball bearing roller  
MICROMANIPULATOR: Counterbalanced, single lever X-Y-Z  
RADIANT TOOL HEAT: Built-in  
WORK PLATFORM: Fixed height. Adjustable height priced separately  
MICROSCOPE: Selection available (ESD types available)  
ILLUMINATOR: Selection available (ESD types available)  
WORK HOLDERS: Selection available (ESD types available)  
DIMENSION: W=24.218" D=22.297" H=11.000"  
WEIGHT: 75 lbs uncreated, or 165 lbs accessorized and crated

[www.acrosemi.com](http://www.acrosemi.com)



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